SUMITOMO BAKELITE CO., LTD.

PRESS RELEASE

Sumitomo Bakelite Co., Ltd.
May 15, 2026

Participation in "ECTC 2026"

a Leading International Conference on Semiconductor Packaging Technologies

Sumitomo Bakelite Co., Ltd. (Head Office: Shinagawa-ku, Tokyo; President and Representative Director: Shinichi Kajiya) will participate in the IEEE 76th Electronic Components and Technology Conference (ECTC 2026), one of the world's largest international conferences on next-generation semiconductor packaging and assembly technologies, including those supporting the evolution of AI semiconductors. The conference will be held from May 26 to 29, 2026, in Orlando, Florida, USA. At ECTC 2026, we will present three technical papers jointly with universities and research partner companies.

Background

With the rapid expansion of AI semiconductors, semiconductor packages are increasingly required to deliver higher performance, reliability, and integration density. We are actively promoting collaboration with external partners to accelerate the development of advanced materials and technologies for next-generation semiconductors.
At ECTC 2026, the Company will present research results related to opto-electronic integrated packaging technologies, glass substrate redistribution layers, and high-thermal-conductivity encapsulation materials for automotive applications. Through these presentations, we aim to deepen technical exchange with academia and industry and to create future business opportunities.

Technical Presentations

■ **Optical RDL Interposer Technology using Polymeric Hybrid Bonding and Waveguide for Integrated CPO (Joint Research with Tohoku University)**

An optical RDL interposer technology for integrated CPO (Co-Packaged Optics) is proposed using a multifunctional photocurable polymer that serves as both a waveguide cladding layer and a dielectric layer for hybrid bonding. This technology enables reliable low-temperature bonding and is expected to contribute to next-generation high-speed optical communication packaging.

■ **Novel Photosensitive Material with Low Shrinkage and Low Dielectric Properties for High-Density RDL in Glass Packaging(Joint Research with Georgia Institute of Technology)**

A novel liquid photosensitive RDL material featuring low curing temperature, low shrinkage, and low dielectric properties was developed. Using this material, high-density copper redistribution layers were successfully formed on glass interposers, demonstrating multilayer wiring with microvias for the first time on glass substrates.

■ **Development of High Thermal Conductivity Molding Materials for Automotive Flip Chip Packages (Joint Research with SPIL and MediaTek)**

High thermal conductivity molding materials for automotive flip-chip packages were developed through optimization of resin composition and alumina filler formulation. These materials achieve both excellent thermal performance and reliability.

Looking Ahead

Sumitomo Bakelite Co., Ltd. has continuously pursued the potential of plastics and contributed to society, the environment, and people's lives through value creation. Going forward, the Company will continue to enhance its global presence through the development of advanced materials technologies.

About IEEE 76th Electronic Components and Technology Conference (ECTC 2026)

Dates: May 26 (Tue) – May 29 (Fri), 2026
Venue: JW Marriott & The Ritz-Carlton Grande Lakes, Orlando, Florida, USA
Website: https://ectc.net/

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